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U.S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

FOREIGN PARENT DOCUMENTS								
		Document Number	Date of Publication	Country	Class	SubClass	Translation	
							Yes	No
L ₇		WO 99/30362	6/17/99	PCT				
L _T		WO 92/18600	10/29/92	PCT				
L _R		0 969 058 A2	1/5/00	EPO				
/	/			/				

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

LT			International Search Report for PCT/US01/02385
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EXAMINER

Luan Thai

Date Considered

9/2002

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INFORMATION DISCLOSURE STATEMENT		Atty. Docket No.: 53434USA8C.009		Serial No.: 09/690,600		
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		Filing Date: October 17, 2000		Group: 3729		
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Examiner Initial	Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
LT	5,068,714	11/26/91	Seipler	357	80	
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